

PCN Number: SM040317 Chgnot.doc rev 13 1/14

Product/Process Change Notification (PCN)

Customer: Digi-Key

Date: 04/03/2017

Customer Part # and/or Lot# affected: A4407KLPTR-T

Originator: Scott Mitti

Phone: 508-854-5627

| Duration of Change: | Permanent X Temporary (explain) |
|---|---------------------------------|
| Summary description of change : Part Change: | Process Change: X Other: |

- 1. Allegro currently manufactures the A4407KLPTR-T at wafer fab, Polar Semiconductor LLC (PSL), Bloomington, MN, USA, utilizing 8" ABCD5 technology. Allegro will be changing wafer fab manufacturing to the 8" ABCD5 technology wafer line at United Microelectronics Corporation (UMC), Hsinshu, Taiwan.
- 2. Allegro will permanently close its wafer probe operations in Worcester, Massachusetts, USA by March 31, 2018. Wafer probe operations will be moved to Allegro MicroSystems Philippines, Inc. (AMPI) located in Manila, Philippines for the part numbers listed in this PCN.
- 3. The above listed device will have an additional final test location: Allegro MicroSystems (Thailand) Co., Ltd. (AMTC).

What is the part or process changing from (provide details)?

- 1. Allegro currently manufactures the A4407KLPTR-T at wafer fab, Polar Semiconductor LLC (PSL), Bloomington, MN, USA, utilizing 8" ABCD5 technology.
- 2. Currently the device listed is probed in Allegro's Worcester facility.
- 3. In addition to the current Allegro MicroSystems, test facility location in Manila Philippines, a second test facility referred to as Allegro MicroSystems (Thailand) Co., Ltd. (AMTC) located in Saraburi, Thailand will be added as a primary site.a second test facility referred to as Allegro MicroSystems (Thailand) Co., Ltd. (AMTC). Saraburi, Thailand will be added as a primary site.

What is the part or process changing to (describe the anticipated impact of this change on form, fit and/or function)?

- 1. Allegro will be changing wafer fab manufacturing to the 8" ABCD5 technology wafer line at United Microelectronics Corporation (UMC), Hsinshu, Taiwan.
- 2. Probe location for the listed device(s) will be moved to AMPI. Allegro is utilizing the same probe equipment, test programs and test methodologies in its Philippine facility as is currently being performed in its US facility. Relocation of probe operations reduces movement of wafers between factories shortening overall cycle time and minimizing





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waferhandling. All expansions of probe capability and capacity will now occur at AMPI to support Allegro's future business growth.

- 3. Allegro will be expanding its manufacturing capabilities with the addition of a new, whollyowned integrated circuit test facility located in Saraburi, Thailand. The same make and model test equipment will be utilized and test site transfer buy off data will be on file for each device before production begins.
- Note: Validation of equivalence within a specific application is at the discretion of the Customer

| PPAP update r | equire | d? | | Yes | | No X |
|--|---|---|--|---|---|--|
| reliability testing required? (If Yes, refer to attached plan) | | | | Yes X | No (explain) | |
| Reliability Qualifica Device: 4407 (94407 Assy Lot #: 1626625 Number of Leads: 24 Tab Location: UMC | 1) | esults | | Package: LP (eTSSOP) Assembly Location: Unisem Lead Finish: 100% Sn Tracking Number: 3614 | | |
| Reason for Qualification | 4407 | (04407 | 71) - 2.2 MHz C | onstant On-Time Buck Regulat | or with | Two External |
| and Two Internal Lin | ear Reg | | | onstant On-Time Buck Regulat valification Results | | |
| | ear Reg | | | | | Two External Requirements Results |
| and Two Internal Lin 4407 (944071), STR# | ar Reg | ulators | Reliability Qu | Test Conditions 85°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, | F | Requirements |
| and Two Internal Lin 4407 (944071), STR# Stress Test | 3614 Abv. | Test # | Reliability Qu Test Method JESD22-A113 / | Test Conditions | s.s. | Reguirements Results |
| and Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning | 3614 Abv. PC | Test # A1 | Reliability Qu Test Method JESD22-A113 / J-STD-020 | Test Conditions 85°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, TC) Ta=130°C, 2 ATM, 85% RH, | 5.S. 231 | Requirements Results 0 Rejects |
| And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST | ar Reg | Test # A1 A2 | Reliability Qu Test Method JESD22-A113 / J-STD-020 JESD22-A110 | Test Conditions 85°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, TC) Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs Ta=12°C, 100% RH, 15 psig, | 5.5. 231 77 | Reguirements Results O Rejects O Rejects |
| And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave | ar Reg | Test # A1 A2 A3 | Reliability Qu Test Method JESD22-A113 / J-STD-020 JESD22-A110 JESD22-A102 | Test Conditions S5°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, TC) Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs Ta=121°C, 100% RH, 15 psig, 0, 96 hrs Ta = -65°C to +175°C, | 5.5. 231 77 77 | Reguirements Results 0 Rejects 0 Rejects 0 Rejects |
| And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature | ar Reg | Test # A1 A2 A3 A4 | Reliability Que Test Method JESD22-A113 / J-STD-020 JESD22-A110 JESD22-A102 JESD22-A104 | Test Conditions SS°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, TC) Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs Ta=121°C, 100% RH, 15 psig, 0, 96 hrs Ta=21°C, 100% RH, 15 psig, 0, 96 hrs Ta = -65°C to +175°C, 0, 500, 1000 Cycles Ta = 125°C, | 5.5. 231 77 77 77 77 | Requirements Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects |
| And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature | Abv. PC HAST AC TC HTOL | Test # A1 A2 A3 A4 B1 | Reliability Que Test Method JESD22-A113 / J-STD-020 JESD22-A100 JESD22-A102 JESD22-A104 JESD22-A108 JESD22-A108 AEC-Q100-008 / JESD22-A108 | Test Conditions 85°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, TC) Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs Ta=12°C, 100% RH, 15 psig, 0, 96 hrs Ta=-65°C to +175°C, 0, 500, 1000 Cycles Ta=125°C, 0, 1000 hrs Ta=150°C, 0, 48 hrs | 231 231 77 77 77 77 77 77 800 | Reguirements Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects |
| And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature Reverse Bias Life Test | Abv. PC HAST AC TC HTOL HTRB | Test # A1 A2 A3 A4 B1 B1 | Reliability Qu Test Method JESD22-A113 / J-STD-020 JESD22-A102 JESD22-A102 JESD22-A104 JESD22-A108 JESD22-A108 AEC-Q100-008 | Test Conditions 85°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, TC) Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs Ta=12°C, 100% RH, 15 psig, 0, 96 hrs Ta = -65°C to +175°C, 0, 500, 1000 Cycles Ta = 125°C, 0, 1000 hrs Ta = 150°C, 0, 1000 hrs | F S.S. 231 77 77 77 77 800 | Reguirements Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects |
| And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature Reverse Bias Life Test Early Life Failure Rate | Abv. PC HAST AC TC HTOL HTRB ELFR | Test # A1 A2 A3 A4 B1 B2 | Reliability Qu Test Method JESD22-A113 / J-STD-020 JESD22-A110 JESD22-A102 JESD22-A104 JESD22-A108 JESD22-A108 JESD22-A108 MEI-Std-883 | Test Conditions S5°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, TC) Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs Ta=121°C, 100% RH, 15 psig, 0, 96 hrs Ta=121°C, 100% RH, 15 psig, 0, 96 hrs Ta== 12°C, 100% RH, 15 psig, 0, 500, 1000 Cycles Ta== 125°C, 0, 1000 hrs Ta== 150°C, 0, 48 hrs Temp conditions and sample size are | F S.S. 231 77 77 77 77 800 | Results Results O Rejects O Rejects O Rejects O Rejects O Rejects O Rejects O Rejects; Ppk>1.67 |
| And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature Reverse Bias Life Test Early Life Failure Rate Wire Bond Pull Electrostatic Discharge Human Body | Abv. 3614 Abv. PC HAST AC TC HTOL HTRB ELFR WBP | Test # A1 A2 A3 A4 B1 B2 C2 | Reliability Question Test Method JESD22-A113 / J-STD-020 JESD22-A110 JESD22-A102 JESD22-A102 JESD22-A104 JESD22-A108 JESD22-A108 JESD22-A108 JESD22-A108 MELSD22-A108 MI-Std-883 Method 2011 AEC-Q100-002 | Test Conditions 85°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC, TC) 7a=130°C, 2 ATM, 85% RH, 0, 96 hrs 7a=12°C, 100% RH, 15 psig, 0, 96 hrs Ta = -65°C to +175°C, 0, 500, 1000 Cycles Ta = 125°C, 0, 48 hrs Ta = 150°C, 0, 48 hrs Temp conditions and sample size are defined in the test method. (after TC Test Conditions, Sampling Size are defined in the Test Method | 231 231 77 77 77 77 77 77 800 | Results Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects; 0 |
| And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature Reverse Bias Life Test Early Life Failure Rate Wire Bond Pull Electrostatic Discharge Human Body Model(STR#3813) | Abv. PC HAST AC TC HTOL HTRB ELFR WBP HBM | Test # A1 A2 A3 A4 B1 B2 C2 E2 | Reliability Qu Test Method JESD22-A113 / J-STD-020 JESD22-A110 JESD22-A102 JESD22-A104 JESD22-A108 JESD22-A108 JESD22-A108 Mil-Std-883 Method 2011 AEC-Q100-002 / JS-001-2014 | Test Conditions SS°C/60% RH, 168 hrs, Peak Rsflow=260°C; MSL2, (HAST, AC, IC) Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs Ta=121°C, 100% RH, 15 psig, 0, 96 hrs Ta=125°C, 0, 1000 hrs Ta= 150°C, 0, 48 hrs Test Conditions, Sampling Size are din the test method In the Test Method Test Conditions, Sampling Si | 231 231 77 77 77 77 77 77 800 | Reguirements Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects; Ppk>1.67 Classification 2 HBM =2.0 kV |

This device qualification is considered to be passing all environmental stress evaluations per the Allegro MicroSystems, 900019 specification and AEC-Q100.

Approved by:

<u>Bob Domoro</u> Bob Demers Product Safety and Reliability Allegro MicroSystems, LLC

Allegro MicroSystems, LLC





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Expected completion date for internal qualification: Complete

Expected PPAP availability date: N/A

Target implementation date: December 2017

Estimated date of first shipment: January 2018

Expected sample availability date: Available Upon Request

| | | | Date Required: |
|-----------------------------------|----|---|-------------------|
| Customer Approval Required | : | | |
| | No | Х | Notification Only |

Please note: It is our intention to inform our customer of changes as early as possible. Under Allegro's procedure for product/process change notification, Allegro strives, based on its technical judgment, to provide notification of significant changes that may affect form, fit or function. However, as Allegro cannot ensure evaluation of product/process changes for each and every application; the customer retains responsibility to validate the impact of a change on its application suitability. If samples are needed for validation of a change, requests may be made via the contact information provided herein. Please contact your Account Manager or local Sales contact for any questions. We would kindly request your consideration so we can meet our target date for implementation. Unless both parties agree to extend the implementation date, this change will be implemented as scheduled.

Customer comments/Conditions of Acceptance:

Approved by: Date: cc: Allegro Sales/Marketing/Quality

Title: